


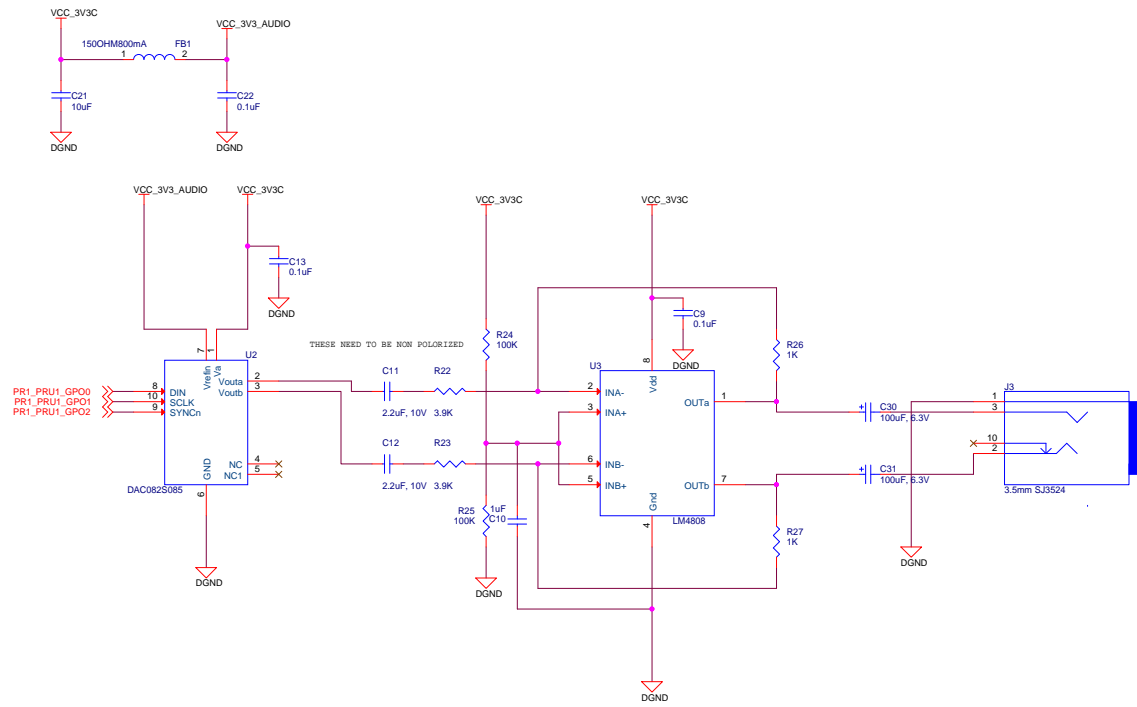
# Beagle Bone Black PRU Cape

-See the Hardware User Guide for board details



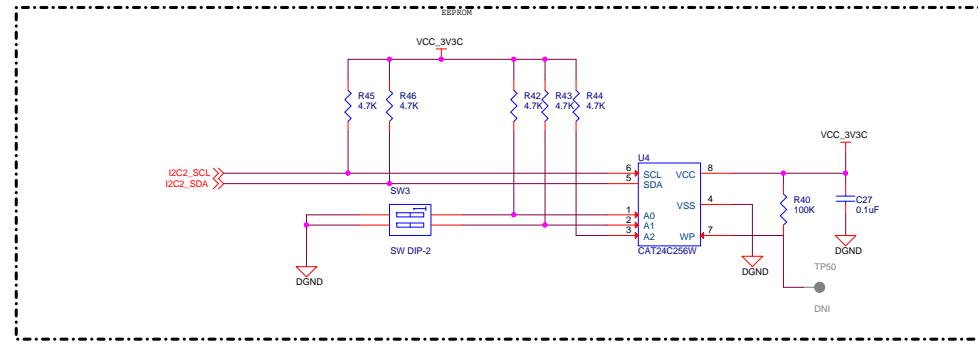
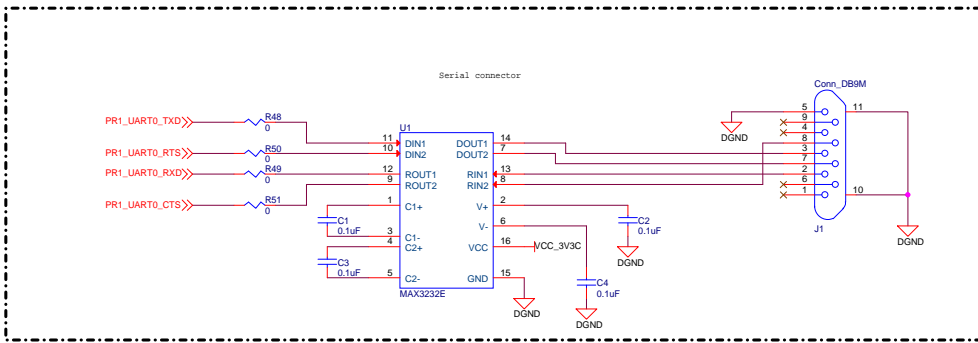
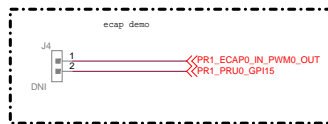
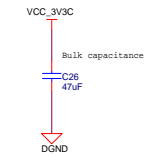
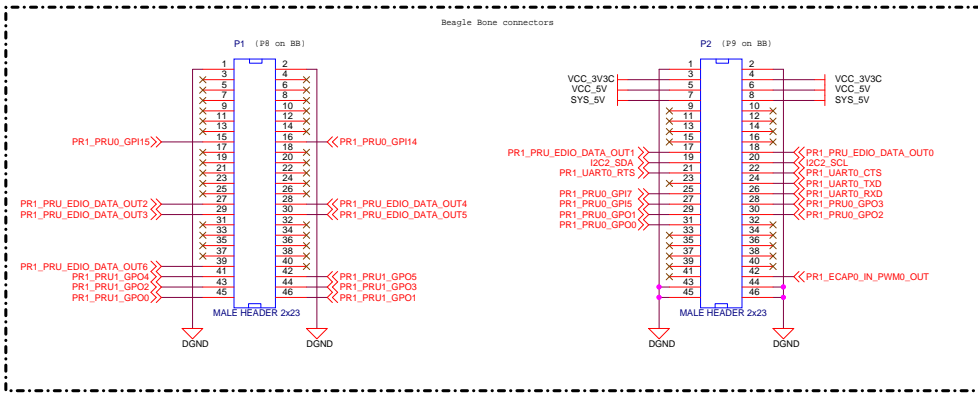
default build

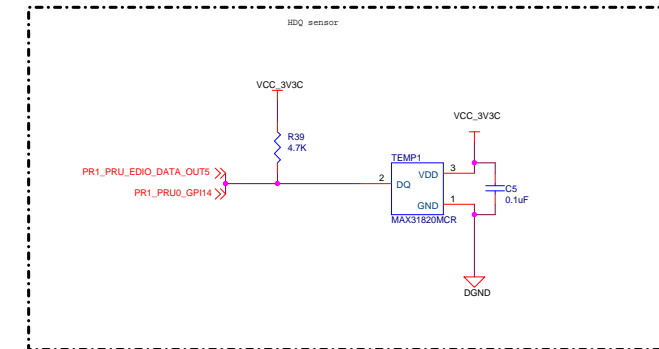
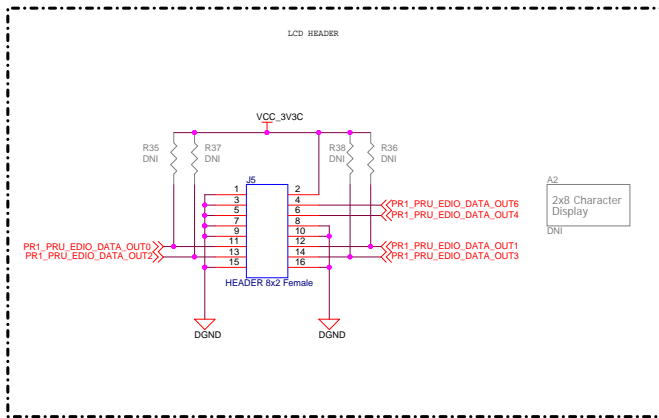
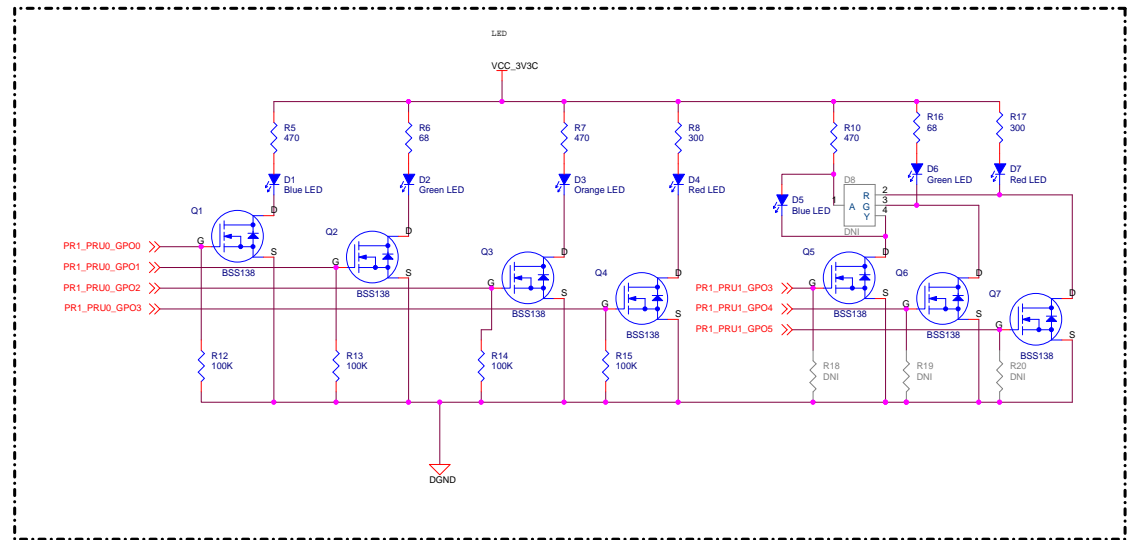
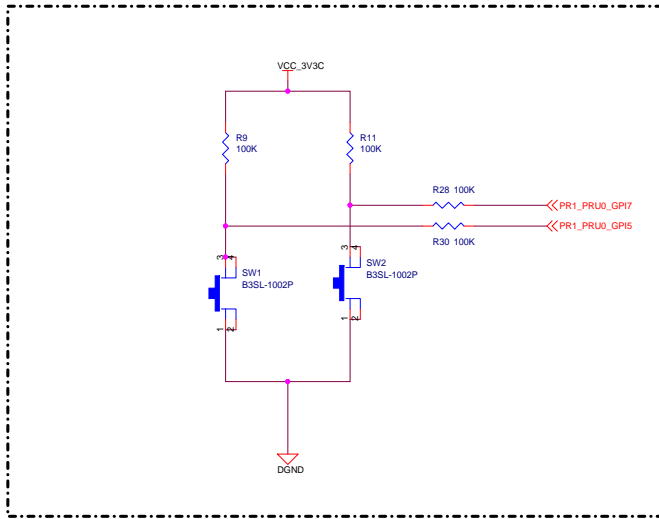
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C	AM335X_ICE_3H0013_2V0A.dsn	Jason Lambert	1.2A	
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default build

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Proto area



default build

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